

## Flexible PCB



- Flexible PCB (1-10 layers)  
Material: Kapton, Polyimide, PET,  
Base copper thickness: 1/3oz, 1/2oz, 1oz, 2oz;  
Base PI thickness: 0.5mil, 0.7mil, 0.8mil, 1mil, 2mil;  
Stiffener: Polyimide, Stainless steel, FR4,  
Surface finish: Immersion Gold/ Silver/Tin, OSP.  
Min width/spacing (1/3oz):0.05mm/0.06mm  
Min width/spacing (1/2oz): 0.06mm/0.07mm

### Flexible PCB Sample Introduction Detailed Product Description

#### Polyimide Flexible Printed Circuit Board / Flexible PCB with metal stiffener

##### Product Description

Touch screen fpc flex pcb board  
Efficient Quotation, Strict Production, Reliable Quality  
Approval: UL, ISO9001  
Fast Delivery

Touch panel fpc connector Flex PCB  
Your Best Choice for Flex PCB and Rigid-flex PCB Manufacturing & Assembly

##### ADVANTAGES:

We product all kinds of Flex pcb and Rigid flex pcb which are widely used in modern portable electronics and devices. Such as Cell phone, key board, LCD module, Disk cable and etc.

1. With 15 years experience in circuit board, Printed Circuit Board field to serve your needs
  2. Competitive circuit board, Printed Circuit Board price with high quality
  3. Excellent service and prompt delivery
  4. Our circuit board, Printed Circuit Board get ISO and UL Certificates and meet ROHS REACH standard
1. Professional & experienced engineers
  2. Competitive price
  3. In time service
  4. Product warranty

## Detailed Specification of Flexible PCB Manufacturing

Technical Specification		
Layers:	1~10 (flex Pcb) and 2~8 (rigid flex)	
Min Panel Size:	5mm x 8mm	
Max Panel Size:	250 x 520mm	
Min Finished board thickness:	0.05mm (1 sided inclusive copper)	
Max Finished board thickness:	0.3mm (2 sided inclusive copper)	
Finished board thickness tolerance:	±0.02~0.03mm	
Material:	Kapton, Polyimide, PET	
Base copper thickness (RA or ED):	1/3 oz, 1/2 oz, 1oz, 2oz	
Base PI thickness:	0.5mil, 0.7mil, 0.8mil, 1mil, 2mil	
Stiffner:	Polyimide, PET, FR4, SUS	
Min Finished hole diameter:	Φ 0.15mm	
Max Finished hole diameter:	Φ 6.30mm	
Finished hole diameter tolerance (PTH):	±2 mil ( ±0.050mm)	
Finished hole diameter tolerance (NPTH):	±1 mil ( ±0.025mm)	
Min width/spacing (1/3oz):	0.05mm/0.06mm	
Min width/spacing (1/2oz):	0.06mm/0.07mm	
Min width/spacing (1oz):	Single layer: 0.07mm/0.08mm	
	Double layer: 0.08mm/0.09mm	
Aspect Ratio	6:01	8:01
Base Copper	1/3Oz--2Oz	3 Oz for Prototype
Size Tolerance	Conductor Width:±10%	W ≤0.5mm
	Hole Size: ±0.05mm	H ≤1.5mm
	Hole Registration: ±0.050mm	
	Outline Tolerance:±0.075mm	L ≤50mm
Surface Treatment	ENIG: 0.025um - 3um	
	OSP:	
	Immersion Tin: 0.04-1.5um	
Dielectric Strength	AC500V	
Solder Float	288°C/10s	IPC Standard
Peeling Strength	1.0kgf/cm	IPC-TM-650
Flammability	94V-O	UL

## **PCB Assembly services:**

SMT Assembly  
Automatic Pick & Place  
Component Placement as Small as 0201  
Fine Pitch QEP - BGA  
Automatic Optical Inspection  
Through-hole Assembly  
Wave Soldering  
Hand Assembly and Soldering  
Material Sourcing  
IC pre-programming / Burning on-line  
Function testing as requested  
Aging test for LED and Power boards  
Complete unit assembly (which including plastics, metal box, Coil, cable assembly etc)  
Packing design

### Conformal coating

Both dip-coating and vertical spray coating is available. Protecting non-conductive dielectric layer that is applied onto the printed circuit board assembly to protect the electronic assembly from damage due to contamination, salt spray, moisture, fungus, dust and corrosion caused by harsh or extreme environments. When coated, it is clearly visible as a clear and shiny material.

### Complete box build

Complete 'Box Build' solutions including materials management of all components, electromechanical parts, plastics, casings and print & packaging material

### Testing Methods

#### AOI Testing

- Checks for solder paste
- Checks for components down to 0201"
- Checks for missing components, offset, incorrect parts, polarity

#### X-Ray Inspection

X-Ray provides high-resolution inspection of:

- BGAs
- Bare boards

#### In-Circuit Testing

In-Circuit Testing is commonly used in conjunction with AOI minimizing functional defects caused by component problems.

- Power-up Test
- Advanced Function Test
- Flash Device Programming
- Functional testing

### Detailed Specification of Pcb Assembly

1	Type of Assembly	SMT and Thru-hole
2	Solder Type	Water Soluble Solder Paste, Leaded and Lead-Free
3	Components	Passives Down to 0201 Size BGA and VFBGA Leadless Chip Carriers/CSP Double-Sided SMT Assembly Fine Pitch to 08 Mils BGA Repair and Reball Part Removal and Replacement- Same Day Service
3	Bare Board Size	Smallest: 0.25x0.25 Inches Largest: 20x20 Inches
4	File Formats	Bill of Materials Gerber Files Pick-N-Place File (XYRS)
5	Type of Service	Turn-Key, Partial Turn-Key or Consignment
6	Component Packaging	Cut Tape Tube Reels Loose Parts
7	Turn Time	15 to 20 days
8	Testing	AOI inspection X-Ray inspection In-Circuit testing Functional test